

FIG. 1

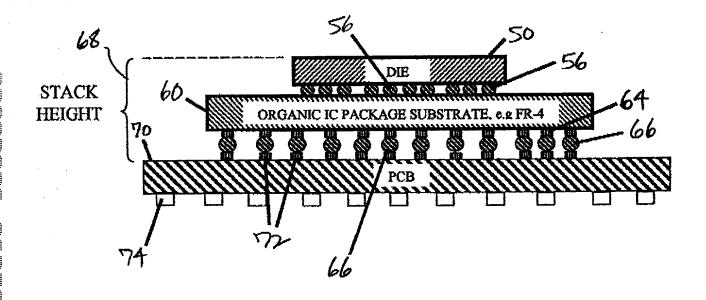


FIG. 2 (PRIOR ART)

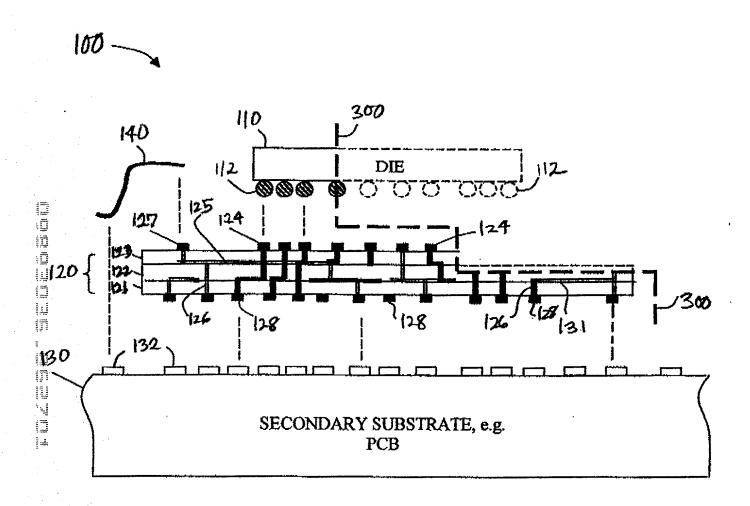
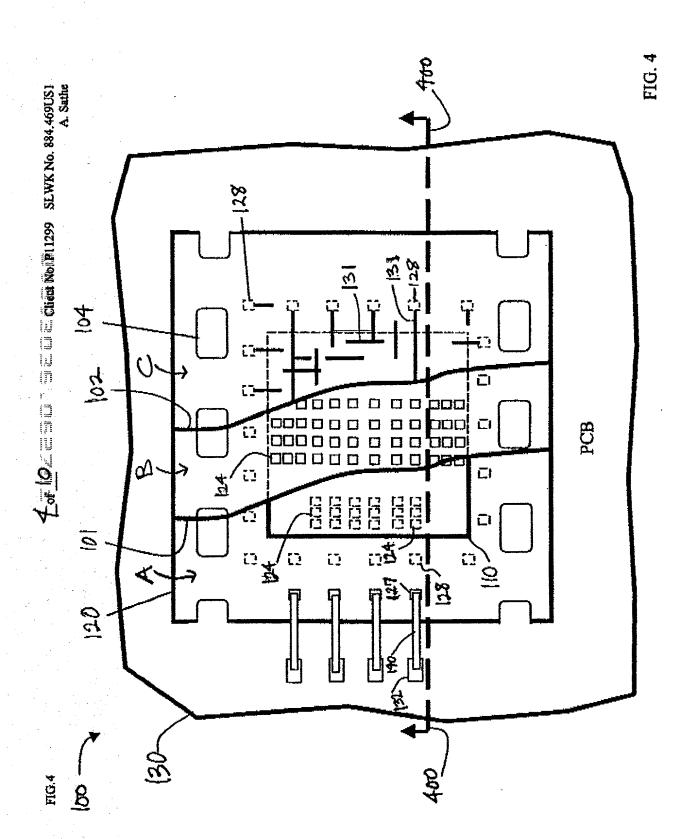


FIG. 3



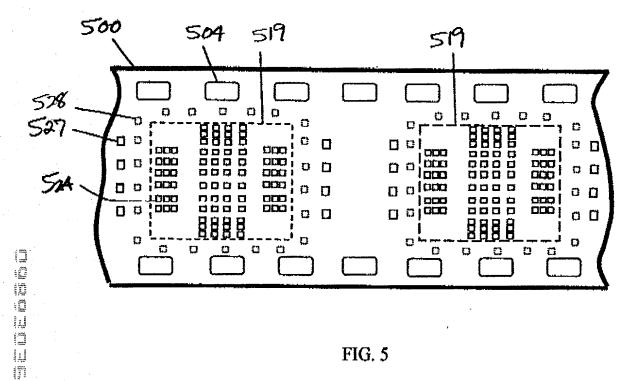


FIG. 5

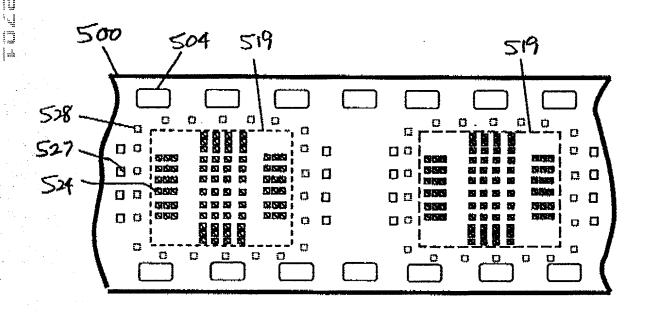


FIG. 6

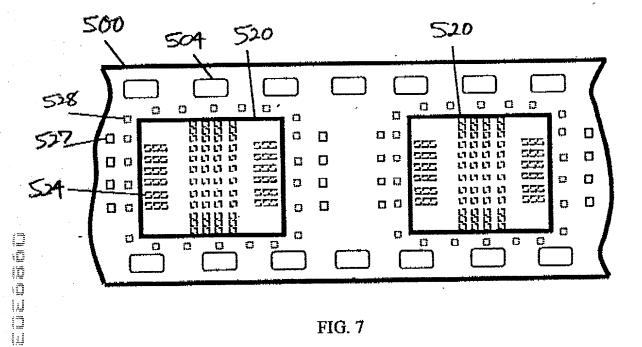


FIG. 7

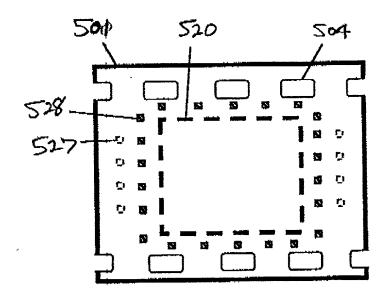


FIG. 8

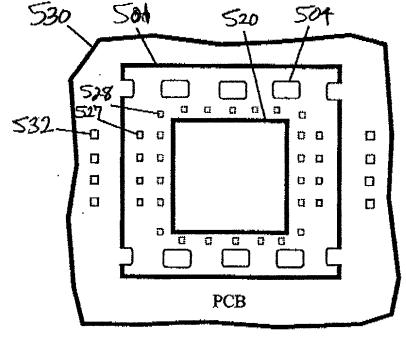


FIG. 9

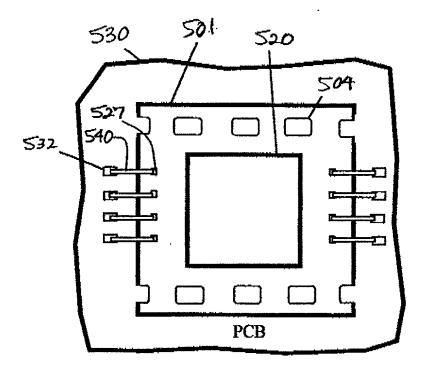
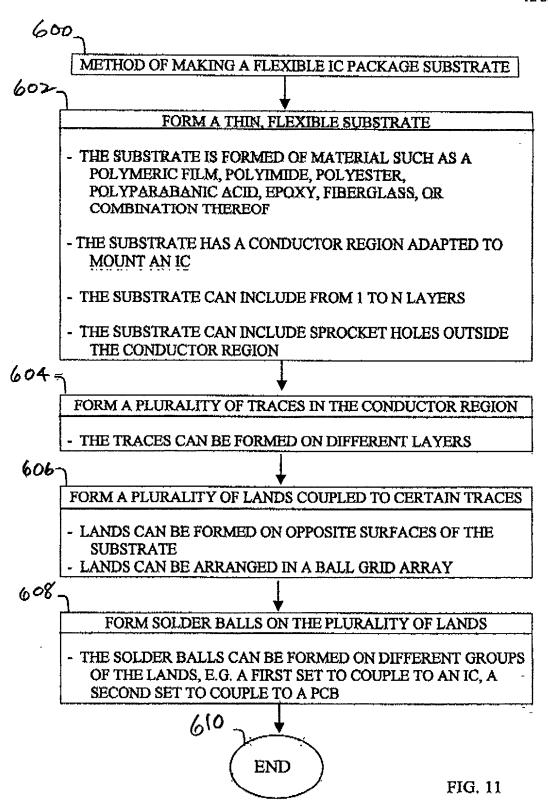
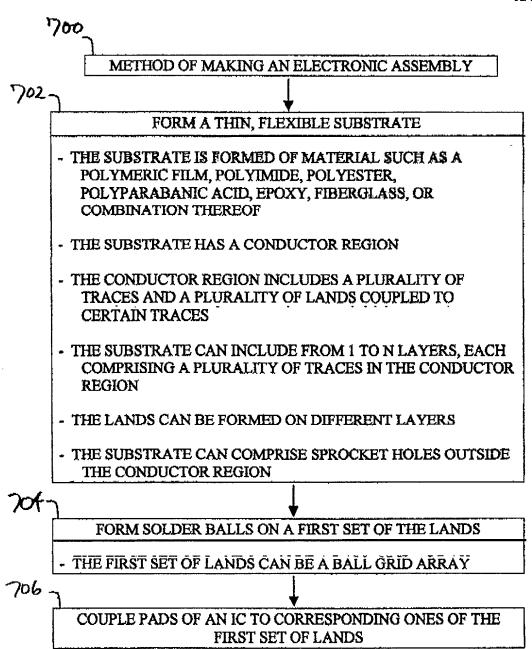


FIG. 10





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MOUNT THE SUBSTRATE ON AN ADDITIONAL SUBSTRATE, E.G. A PCB

EMPLOY EITHER OR BOTH OF THE FOLLOWING:

- USE BGA BETWEEN SUBSTRATE AND PCB
 - FORM SOLDER BALLS ON A SECOND SET OF THE LANDS
 - COUPLE ONES OF THE SECOND SET OF LANDS TO CORRESPONDING TERMINALS ON THE PCB
- USE LEADS BETWEEN SUBSTRATE AND PCB
 - COUPLE LEADS, E.G. WIRES, BETWEEN CORRESPONDING ONES OF A THIRD SET OF LANDS AND ADDITIONAL TERMINALS OF THE PCB

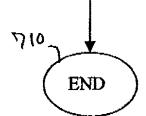


FIG. 12B